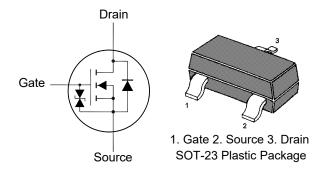
MKA02N020UK

N-Channel Enhancement Mode MOSFET

Features

- · Surface-mounted package
- Extremely low threshold voltage
- Built-in G-S Protection Diode
- Typical ESD Protection HBM Class 1B

Classification	Voltage Range(V)
0A	< 125
0B	125 to < 250
1A	250 to < 500
1B	500 to < 1000
1C	1000 to < 2000
2	2000 to < 4000
3A	4000 to < 8000
3B	≥ 8000



Application

- Portable appliances
- · Battery management

Absolute Maximum Ratings (at Ta = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit V	
Drain Source Voltage	V _{DS}	20		
Gate Source Voltage	V _{GS}	V _{GS} ± 12		
Drain Current	l _D	6	Α	
Peak Drain Current, Pulsed 1)	I _{DM}	30	Α	
Total Power Dissipation 2)	P _{tot}	1.25	W	
Operating Junction and Storage Temperature Range	T _j , T _{stg}	- 55 to + 150	°C	

Thermal Resistance Ratings

Parameter	Symbol	Max.	Unit	
Thermal Resistance from Junction to Ambient ²⁾	$R_{\theta JA}$	100	°C/W	

 $^{^{1)}}$ Pulse Test: Pulse Width ≤ 100 μs, Duty Cycle ≤ 2%,Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$.



²⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air, t ≤ 10 s.

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Characteristics at Ta = 25°C unless otherwise specified

Parameter	Symbol	Min.	Тур.	Max.	Unit
STATIC PARAMETERS	•				
Drain-Source Breakdown Voltage at I _D = 250 μA	BV _{DSS}	20	-	-	V
Drain-Source Leakage Current at V _{DS} = 20 V	I _{DSS}	-	-	1	μA
Gate Leakage Current at V _{GS} = ± 10 V	lgss	-	-	± 10	μA
Gate-Source Threshold Voltage at $V_{DS} = V_{GS}$, $I_D = 250 \mu A$	V _{GSth}	0.4	-	1	V
Drain-Source On-State Resistance at V_{GS} = 4.5 V, I_D = 6 A at V_{GS} = 2.5 V, I_D = 5 A at V_{GS} = 1.8 V, I_D = 4 A	R _{DS(on)}	- - -	- - -	20 24 35	mΩ
DYNAMIC PARAMETERS					
Forward Transconductance at $V_{DS} = 5 \text{ V}$, $I_D = 6 \text{ A}$	g fs	-	14	-	S
Gate resistance at $V_{DS} = 0 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$	Rg	-	2.4	-	Ω
Input Capacitance at $V_{DS} = 10 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$	Ciss	-	698	-	pF
Output Capacitance at $V_{DS} = 10 \text{ V}$, $V_{GS} = 0 \text{ V}$, $V_{GS} = 10 \text{ MHz}$	Coss	-	107	-	pF
Reverse Transfer Capacitance at V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz	Crss	-	83	-	pF
Gate charge total at V_{DS} = 10 V, I_D = 6 A, V_{GS} = 4.5 V at V_{DS} = 10 V, I_D = 6 A, V_{GS} = 2.5 V	Qg	- -	12.4 7.2	-	nC
Gate to Source Charge at V_{DS} = 10 V, I_D = 6 A, V_{GS} = 4.5 V	Qgs	-	1.4	-	nC
Gate to Drain Charge at V_{DS} = 10 V, I_D = 6 A, V_{GS} = 4.5 V	Q_{gd}	-	3.7	-	nC
Turn-On Delay Time at V_{DS} = 10 V, V_{GS} = 4.5 V, I_D = 6 A, R_g = 3.3 Ω	t _{d(on)}	-	14.5	-	ns
Turn-On Rise Time at V_{DS} = 10 V, V_{GS} = 4.5 V, I_D = 6 A, R_g = 3.3 Ω	t _r	-	48	_	ns
Turn-Off Delay Time at V_{DS} = 10 V, V_{GS} = 4.5 V, I_{D} = 6 A, R_{g} = 3.3 Ω	t _{d(off)}	-	18.6	-	ns
Turn-Off Fall Time at V_{DS} = 10 V, V_{GS} = 4.5 V, I_D = 6 A, R_g = 3.3 Ω	t _f	-	7.4	-	ns
Body-Diode PARAMETERS					
Diode Forward Voltage at $I_S = 1 A$, $V_{GS} = 0 V$	V _{SD}	-	-	1.3	V
Body-Diode Continuous Current	Is	-	-	6	Α
Body Diode Reverse Recovery Time at Is = 6 A, di/dt = 100 A / µs	t _{rr}	-	6.5	-	nS
Body Diode Reverse Recovery Charge at I _S = 6 A, di/dt = 100 A / μs	Qrr	-	2	-	nC



Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

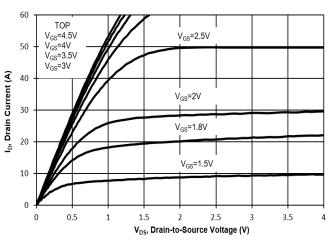


Fig. 2 Typical Transfer Characteristics

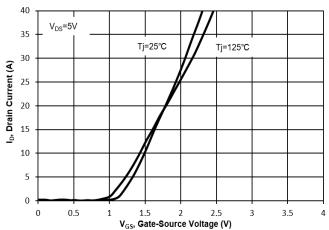


Fig. 3 On-Resistance vs. Drain Current

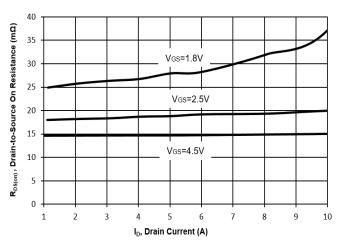


Fig. 4 On-Resistance vs. Gate-Source Voltage

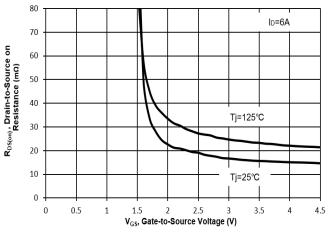


Fig. 5 On-Resistance vs.T_j

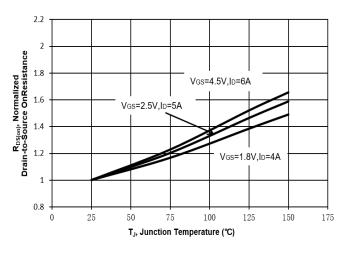
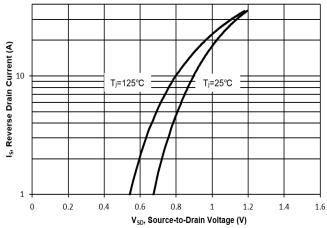


Fig. 6 Typical Body-Diode Forward Characteristics





Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

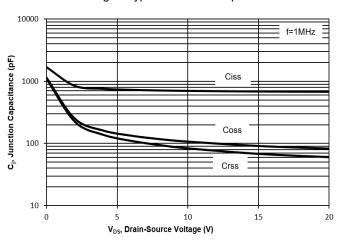


Fig. 8 Drain-Source Leakage Current vs. Tj

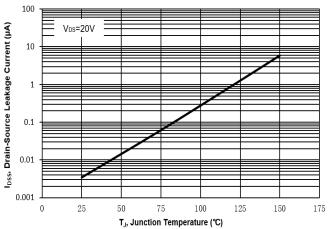


Fig. 9 $V_{(BR)DSS}$ vs. Junction Temperature

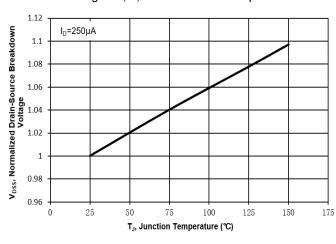


Fig. 10 Gate Threshold Variation vs. T_j

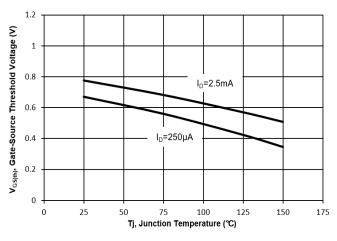
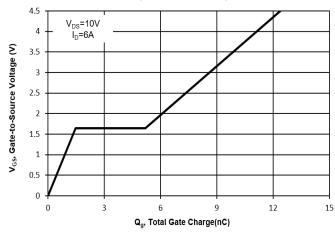


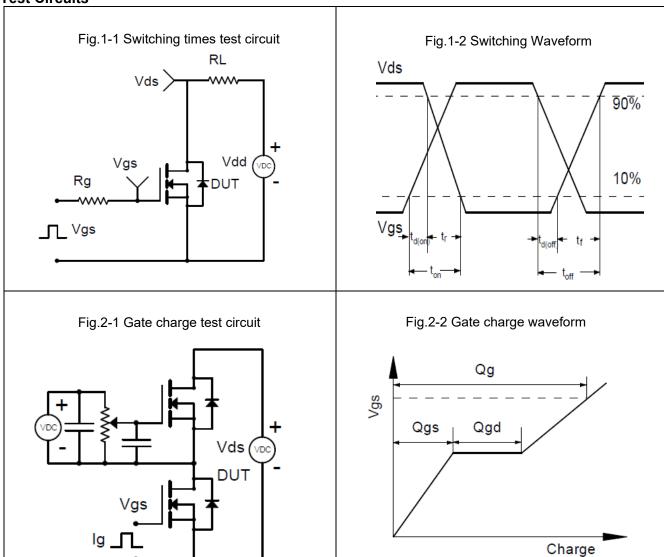
Fig. 11 Gate Charge





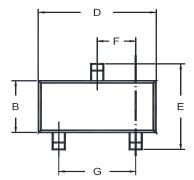
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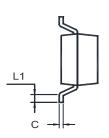
Test Circuits

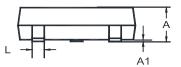


Package Outline (Dimensions in mm)

SOT-23

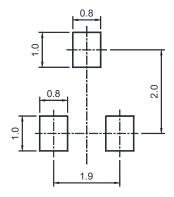






Unit	Α	A1	В	С	D	Е	F	G	L	L1
mana	1.20	0.100	1.40	0.19	3.04	2.6	1.02	2.04	0.51	0.2
mm	0.89	0.013	1.20	0.08	2.80	2.2	0.89	1.78	0.37	MIN

Recommended Soldering Footprint



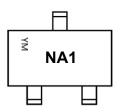
Packing information

doking inioi	mation					
Package	Tape Width	Pitch		Reel Size		
	(mm)	mm	inch	mm	inch	Per Reel Packing Quantity
SOT-23	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

- " NA1 " = Part No.
- " YM " = Date Code Marking
- " Y " = Year
- " M " = Month

Font type: Arial



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